



Material Composition Declaration
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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-21.1	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x	Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information
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Supplier Information

Company name* onsemi	Company unique ID	Unique ID Authority	Response Date* 2023-09-25
Contact Name Product-Env-Stewards	Title - Contact Product Enviro Compliance	Phone - Contact* NA	Email - Contact* Product-Env-Stewards@onsemi.com
Authorized Representative* Product-Env-Stewards	Title - Representative Product Enviro Compliance	Phone - Representative* NA	Email - Representative* Product-Env-Stewards@onsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
	STK551U3A2A-E	3phase inverter HIC	2023-09-25		VN2	16700.0	mg	Each

Manufacturing Process Information

Terminal Plating / Grid Array Material	Terminal Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	Number of Reflow Cycles
Matte Tin (Sn) - annealed	CU Alloy	NA	0 C	30 seconds	3

Comments

For more information regarding material composition please refer to page 3

RoHS Material Composition Declaration		Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).		
<p>Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.</p>			
RoHS Declaration *	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions		Supplier Acceptance * Accepted
Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.			
Exemption List Version	EL-2011/534/EU		
Declaration Signature			
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.			
Supplier Digital Signature	Rastislav Drska		

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Ceramic Substrate	4828.54	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		79.6709	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		321.5807	mg
			B	Nickel (Ni)	7440-02-0		7.7257	mg
			Supplier	Copper (Cu)	7440-50-8		317.2351	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		0.9657	mg
			Supplier	Aluminum (Al)	7429-90-5		4101.3618	mg
Chip Parts	52.8	mg	Supplier	Silver (Ag)	7440-22-4		1.1616	mg
			Supplier	Epoxy resins	129915-35-1		0.4066	mg
			Supplier	Tin (Sn)	7440-31-5		1.489	mg
			Supplier	Magnesium Monoxide (MgO)	1309-48-4		0.1056	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.7445	mg
			Supplier	Ceramic	12013-47-7, 12047-27-7		8.543	mg
			Supplier	Phenolic resins	Proprietary Data		0.0528	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0053	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		33.8026	mg
			B	Nickel (Ni)	7440-02-0		2.4024	mg
			A	Lead Oxide (PbO)	1317-36-8	7c	0.0581	mg
			Supplier	Copper (Cu)	7440-50-8		3.5323	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.4963	mg
Die	36.19	mg	Supplier	Silicon (Si)	7440-21-3		36.19	mg
Die Attach	1.77	mg	Supplier	Silver (Ag)	7440-22-4		1.2162	mg
			Supplier	Other Epoxy resins	Proprietary Data		0.2683	mg
			Supplier	Tin (Sn)	7440-31-5		0.1749	mg
			Supplier	Other Metal Oxide	Proprietary Data		0.0678	mg
			B	Antimony (Sb)	7440-36-0		0.0161	mg
			B	Antimony Pentoxide (Sb2O5)	1314-60-9		0.0267	mg
Heat Sink	1315.9	mg	Supplier	Silver (Ag)	7440-22-4		12.8958	mg
			Supplier	Copper (Cu)	7440-50-8		1303.0042	mg
Lead Frame	843.67	mg	Supplier	Tin (Sn)	7440-31-5		0.5062	mg
			Supplier	Copper (Cu)	7440-50-8		843.1638	mg
Mold Compound-Black	9518.32	mg		Brominated epoxy resin	proprietary data		190.3664	mg

			Supplier	Phenolic Resin	Proprietary Data		571.0992	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		190.3664	mg
			B	Antimony Trioxide (Sb2O3)	1309-64-4		285.5496	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		951.832	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		666.2824	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		6662.8242	mg
Plating	11.8	mg	Supplier	Tin (Sn)	7440-31-5		5.9	mg
			B	Nickel (Ni)	7440-02-0		5.9	mg
Solder Ball	44.27	mg	Supplier	Silver (Ag)	7440-22-4		1.3724	mg
			Supplier	Tin (Sn)	7440-31-5		42.57	mg
			B	Antimony (Sb)	7440-36-0		0.0044	mg
			Supplier	Copper (Cu)	7440-50-8		0.3232	mg
Wire Bond	46.74	mg	Supplier	Silicon (Si)	7440-21-3		0.0047	mg
			Supplier	Aluminum (Al)	7429-90-5		46.7353	mg